



Lead-free, no-clean and halide free solder wire

Description:

Interflux® **IF 14-22** lead-free, no-clean solder wire contains no rosin, no halides and is recommended when soldering in **class 3** (IPC-A-610).

The body of the IF 14 flux carrier can almost fully evaporate during soldering (rather than carbonising).

The residues can easily be removed by hand (brush).

IF 14-22 has increased flux content compared to the IF 14-16. It has a larger process window and is suitable for high thermal mass through hole soldering.

IF 14-22 can give a bit more residues than the standard IF 14-16.



Products pictured may differ from the product delivered



Key properties

- Non sticky residue, easily removable by hand
- No colophony fumes
- Classification to IPC and EN: **RE LO**
- Absolutely halogen free
- Long tip-life
- Very good wetting on Cu, Ag, Sn ...

Availability

Flux type: IF 14
Flux content: 2,2% w/w

alloy	melting point	diameters					
		0,35	0,50	0,70	1,00	1,50	2,00
Sn96,5Ag3Cu0,5	217°C—219°C	●	●	●	●	●	●
Sn96,5Ag3,5	221°C	●	●	●	●	●	●
Sn95,5Ag3,8Cu0,7	217°C-219°C	●	●	●	●	●	●
Sn99Ag0,3Cu0,7	217°C-227°C	●	●	●	●	●	●
Sn99,3Cu0,7	227°C	●	●	●	●	●	●
Sn99Q ^C (*)	232°C		●	●	●	●	●

● = available

● = upon request

(*) Sn99Q^C is an alloy designated for reworking LMPA™-Q solder joints



Work Instructions

Manual soldering

The advised working temperature is between 320°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered. Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of solder ensures a

drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety datasheet of the product



Test results

Conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	RE L0	J-STD-004
	F-SW 33	DIN 8511
	1.2.3	ISO 9454
qualitative copper mirror	pass	J-STD-004 IPC-TM-650 2.3.32
qualitative halide		
silver chromate (Cl, Br)	pass	J-STD-004 IPC-TM-650 2.3.33
spot test (F)	pass	J-STD-004 IPC-TM-650 2.3.35.1
quantitative halide	0,00%	J-STD-004 IPC-TM-650 2.3.35
Environmental		
SIR test	pass	J-STD-004 IPC-TM-650 2.6.3.3
	pass	TA-NWT-000078 13.1.4
qualitative corrosion, flux	pass	J-STD-004 IPC-TM-650 2.6.15
electro chemical migration	pass	TA-NWT-000078 13.1.5



Packaging

Spools of 10g, 100g, 500g and 1000g

Not all diameters are available on all
spool sizes

Trade name : IF14-22 Lead-Free, Halide Free, No-Clean Solder Wire

Disclaimer

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